Product Lineup

Thermalnite®

▶Thermalnite®

Features: Fiber length D50 approx. 14 μm

Applications: Thermal interface sheets, encapsulants, adhesives, gap fillers, thermoplastics

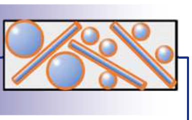
▶Thermalnite® Powder

Features: Fiber length D50 approx. 10 μm

Applications: Grease, adhesives, underfill

※ Surface treatment is also available for the above products.

Hybrid Filler



▶Hybrid Filler – Small Particles

Features: Short Thermalnite fibers +spherical AlN, max particle size: 80 μm

Applications: Encapsulants, adhesives, grease, gap fillers, thermoplastics

▶Hybrid Filler – Large Particles

Features: Short Thermalnite fibers +spherical AlN, max particle size: 300 μm

Applications: Gap fillers, encapsulants, thermoplastics

※ Surface and water-resistant treatment is also available for the above products.

Thermal Interface Sheets

▶Low Thermal Resistance Sheets

Thickness: 0.1, 0.2, 0.5, 1.0 mm

Sizes: A4, A5

Target Devices: Controllers, power supplies, optical transceivers, SSDs, LEDs, LDs, etc.

▶High Thermal Conductivity Sheets

Thickness: 0.5, 1.0 mm

Target Devices: Power modules, motor drive units, communication module ICs, CPUs, etc.

Ceramic Substrates

▶High-Strength AlN Substrates (In-Plane Oriented)

Thermal Conductivity: 170, 200, 230 W/m·K (under development)

Thickness: 0.2–1 mm

Size: A4

Applications: Power modules, LED/LD modules, etc.

U-MAP Co., Ltd.
Ultimate Material and Processing

Please Contact us here▶